



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-08-03
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH3R04QRL	HNRH*E65L81E	A	ZA41	2015-08-03
Amount		UoM	Unit type	ST ECOPACK Grade
400.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
RAD	6.4 - 10.17 - 3.24	2	Through-hole	
Comment	Package: DO 15			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HNRH*E65L81E					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	1.711	mg	supplier	die	Silicon (Si)	7440-21-3		1.617	mg	945029	4040
				supplier	metallization	Aluminium (Al)	7429-90-5		0.012	mg	7018	30
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	1170	5
				supplier	metallization	Nickel (Ni)	7440-02-0		0.008	mg	4678	20
				supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	4678	20
				supplier	Passivation	Silicon Oxide	7631-86-9		0.011	mg	6433	28
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	585	3
				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	1754	8
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.013	mg	7602	33
				supplier	polymer die coating	Probimide	proprietary		0.036	mg	21053	90
Leadframe	Copper & its alloys	286.453	mg	supplier	alloy	Copper (Cu)	7440-50-8		286.318	mg	999529	715795
				supplier	alloy	Zinc (Zn)	7440-66-6		0.011	mg	38	28
				supplier	alloy	Iron (Fe)	7439-89-6		0.028	mg	98	70
				supplier	alloy	Phosphorus (P)	12185-10-3		0.096	mg	335	240
Soft solder	Solder	4.791	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.431	mg	924859	11078
				supplier	solder	Silver (Ag)	7440-22-4		0.240	mg	50094	600
				supplier	solder	Tin (Sn)	7440-31-5		0.120	mg	25047	300
Encapsulation	Other organic materials	103.052	mg	supplier	mold compound	Quartz	14808-60-7		80.381	mg	780004	200953
				supplier	mold compound	epoxy resin	29690-82-2		14.943	mg	145004	37358
				supplier	mold compound	phenol resin	9003-35-4		7.213	mg	69994	18033
				supplier	mold compound	Carbon Black	1333-86-4		0.515	mg	4997	1288
connections coating	Solder	3.993	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.993	mg	1000000	9983